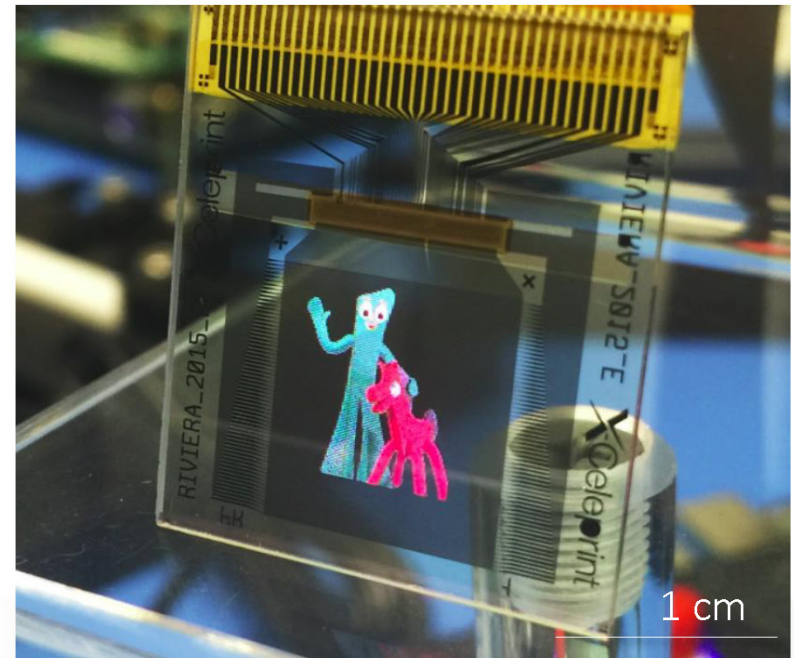
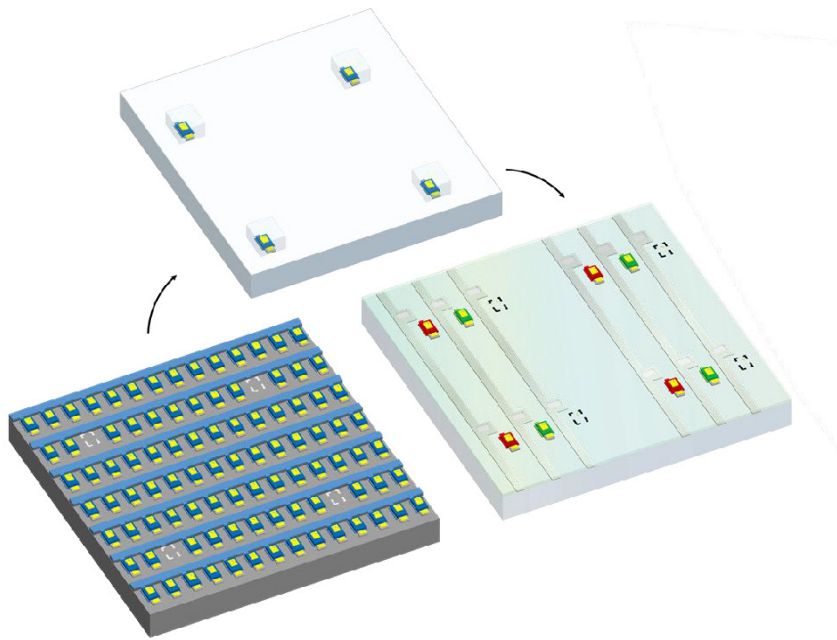


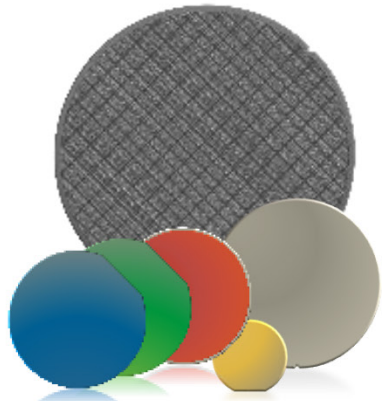
Transfer Printed Microscale Inorganic LEDs (iLEDs) for Display Applications

Chris Bower, X-Celeprint Inc.



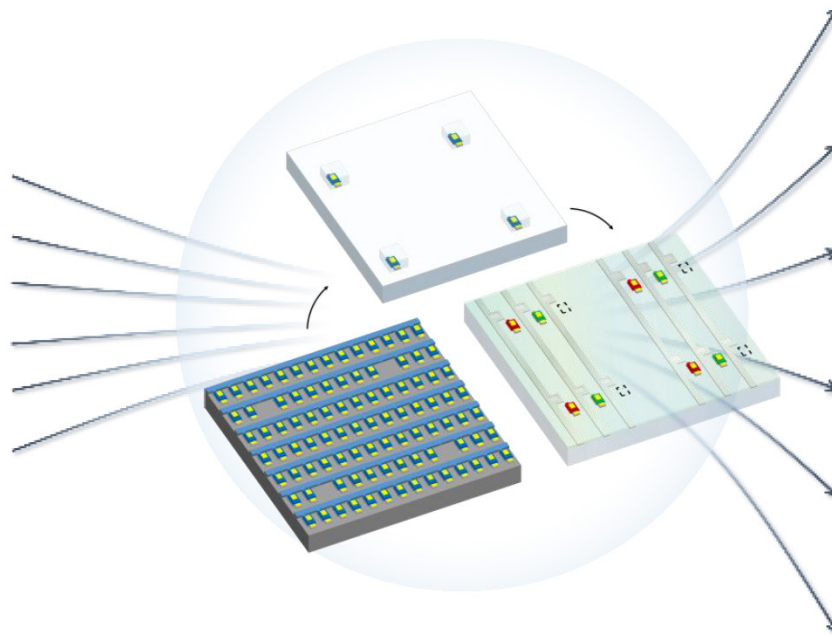
“Micro-Transfer Printing” (μ TP): from wafer to panel

...for advanced displays of all sizes:



Wafer Fabricated Devices
Single-crystal
Fine lithography
(ICs, LEDs, Lasers, etc...)

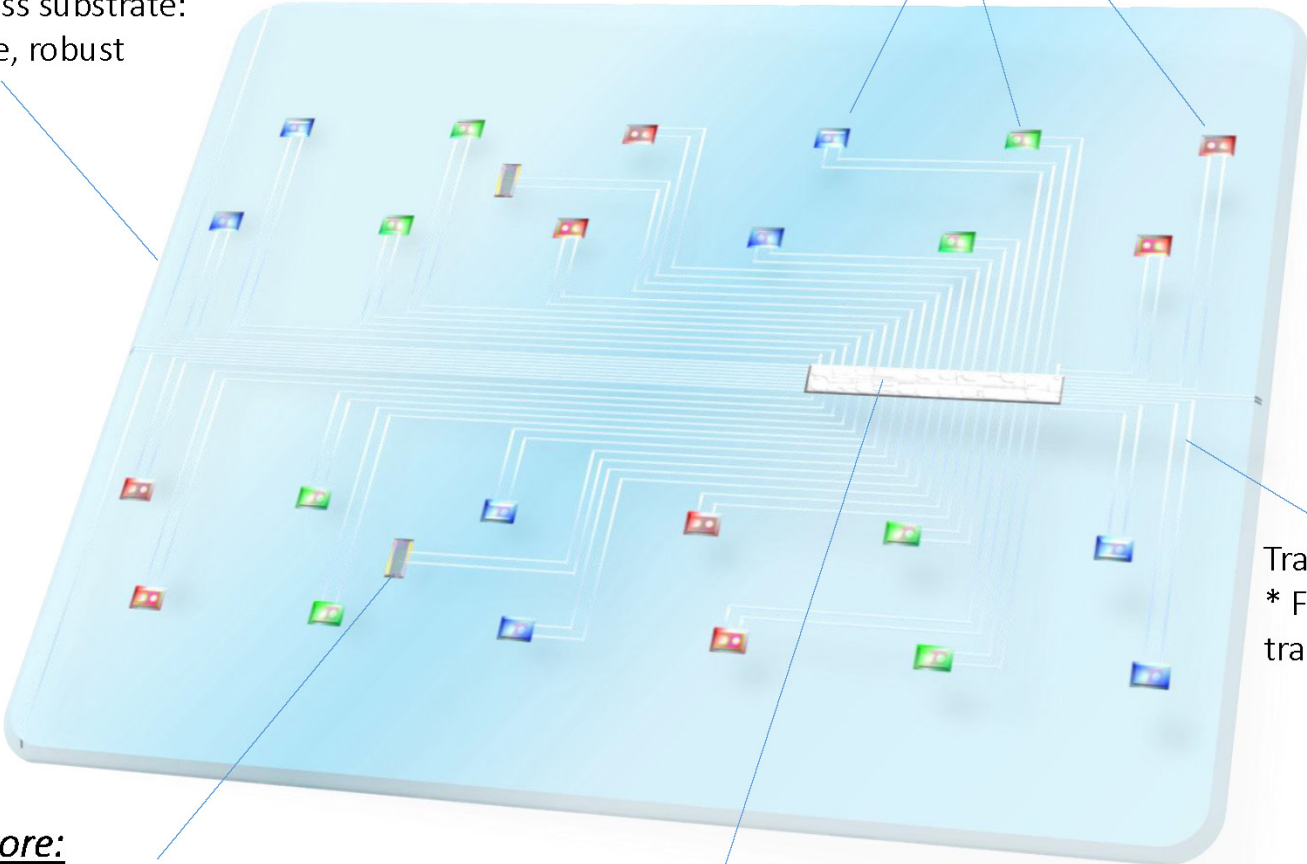
- High performance,
- Large variety of function,
- Miniaturized/miniaturizable.



Unconstrained Material Selection for Next Generation Displays

Plastic or glass substrate:
Light, flexible, robust

R/G/B μ -iLEDs:
low power consumption and bright, defect tolerance



Transparent
* Fine and/or
transparent wiring level

Room to do more:

The sparsely integrated μ LEDs allow for new functions: μ -sensors, power harvest, gesture sense, image capture, RF, etc...

μ ICs:
CMOS performance, embedded memory and novel design concepts
* the printed μ C should control a cluster of pixels

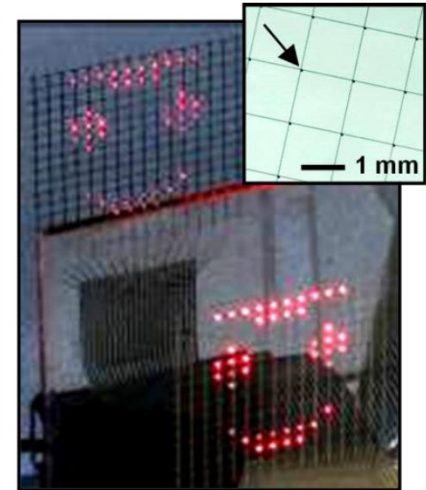


Wafer-Made Micro-Components for Displays: *where to begin?*

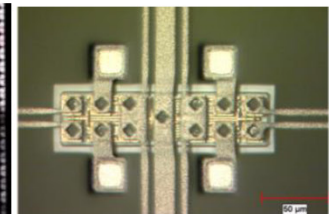
- Inorganic LED (iLED) emitters
- Single-crystal transistors
- Micro-ASIC pixel circuits
- Sensors and actuators
- Photodiodes and photovoltaic cells
- Light management structures
- [Transparent] conductors
- RF amplifiers
- ...



Science 325, 977 (2009). — 5 mm



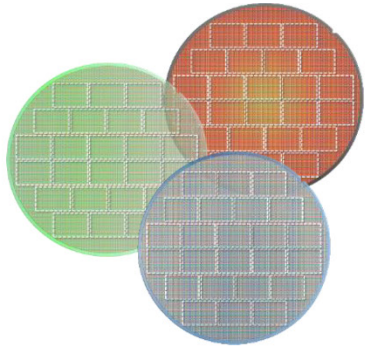
— 5 mm



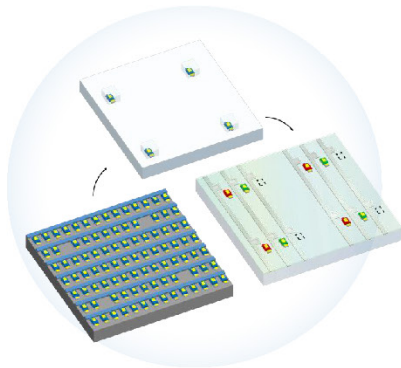
Bower, C. A., et al. "Active-matrix OLED display backplanes using transfer-printed microscale integrated circuits." *IEEE, 2010 Electronic Components and Technology Conference*. 2010.

PMiLED Fabrication Overview

Micro LED source wafers:
(one per color)

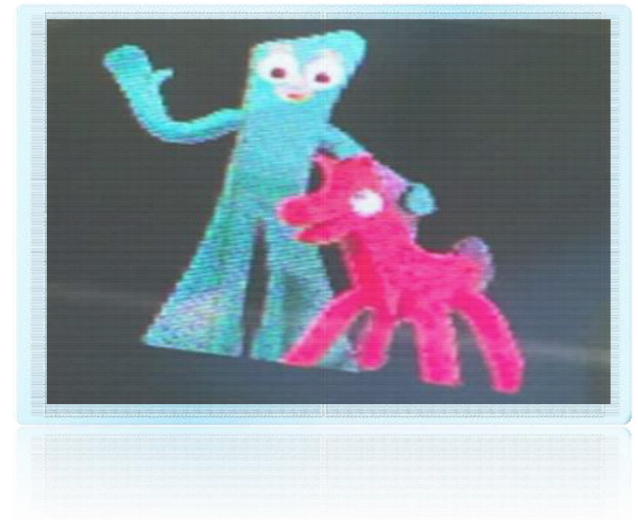


Micro Transfer Printing
to display substrate

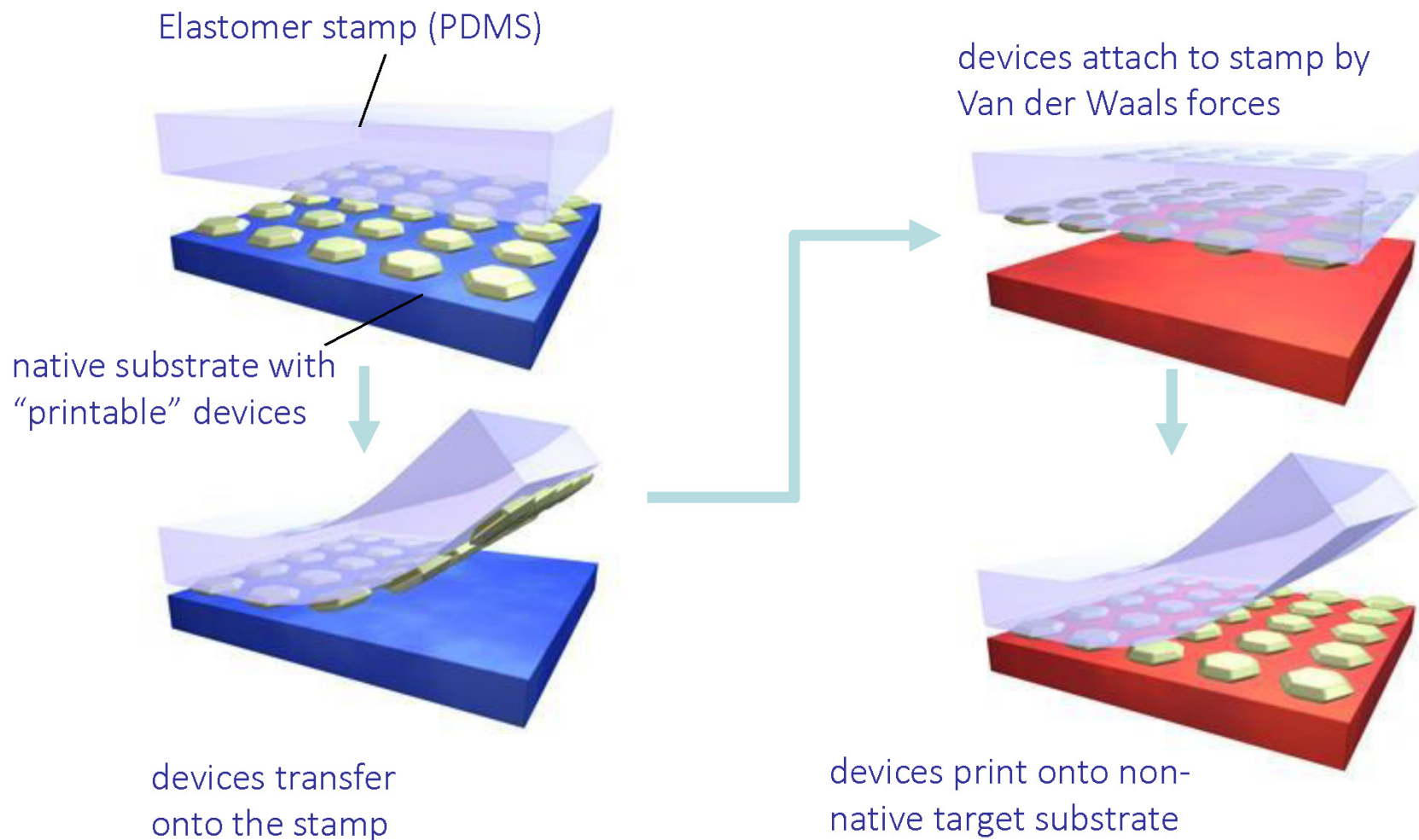


Interconnection on Display
Substrate

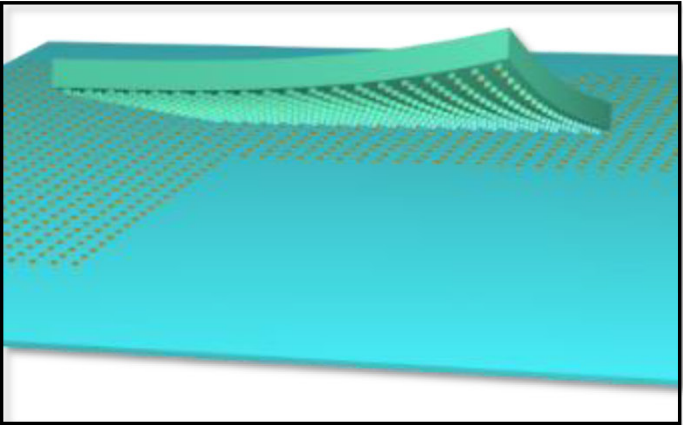
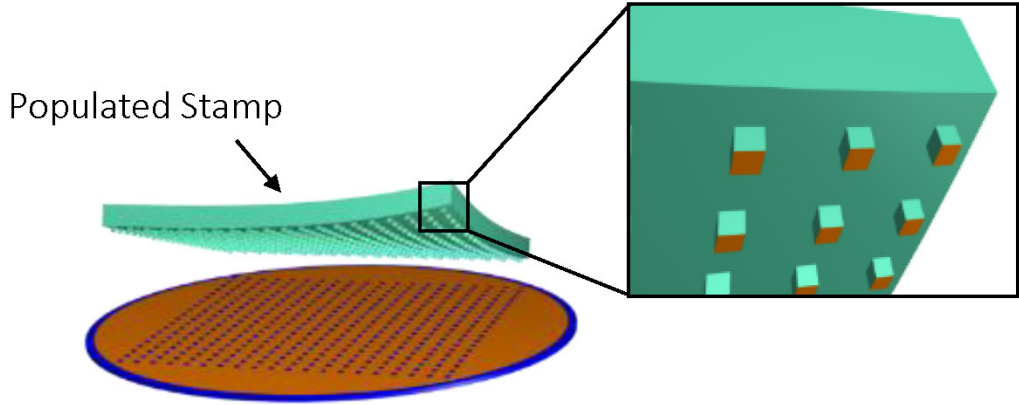
- Large-area displays
- Many panels per source wafer



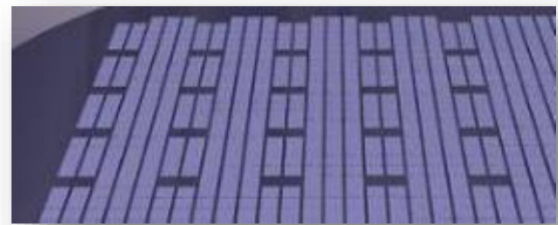
Micro assembly with an elastomer stamp



Precise, Deterministic Dispersal of Micro Devices



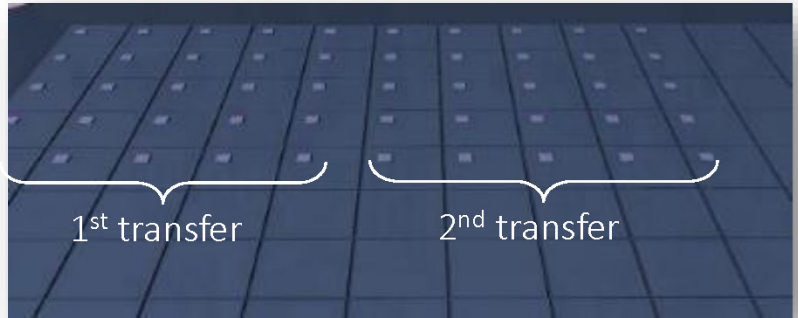
Source Wafer



Densely packed micro components

Printing
→

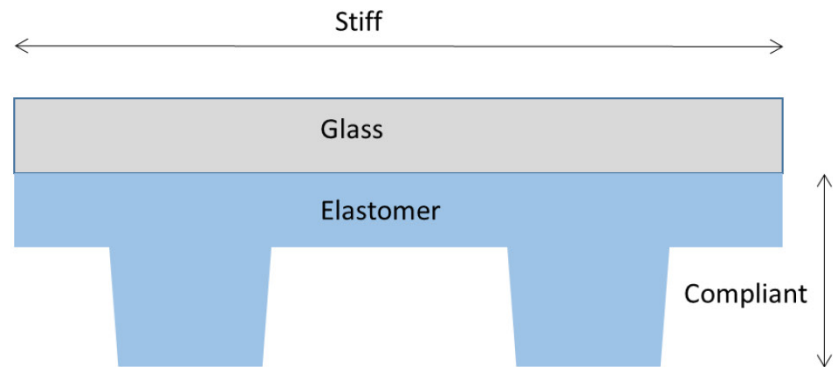
Non-native "Target" Substrate



Dispersed micro components

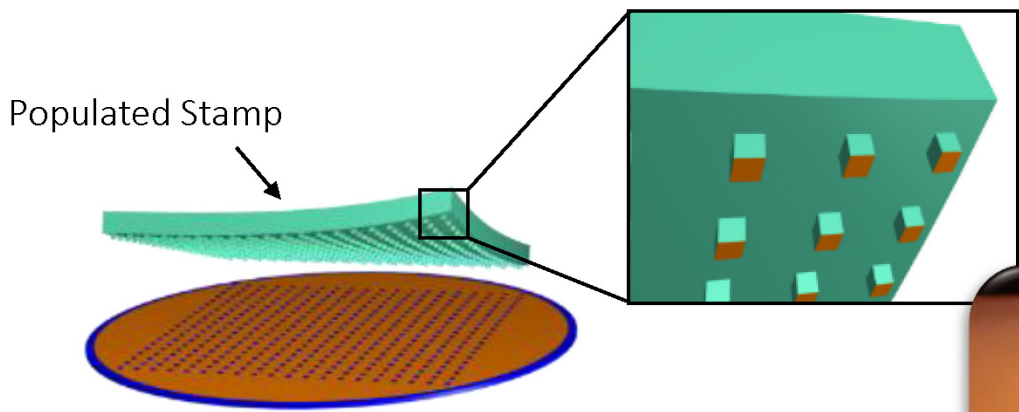
Elastomer Stamp:

Microscale manipulation with macroscale scalability

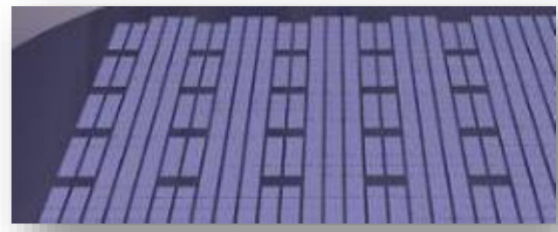


- Naturally compliant in the Z Direction: contacts real-world surfaces over large areas
- Laterally stiff: maintains lateral registration
- Soft contact: Ideal for handling fragile & thin semiconductor devices
- Transparent: Facilitates optical alignment through the stamp during printing
- Low cost: Injection molded with inexpensive materials (glass & silicone)

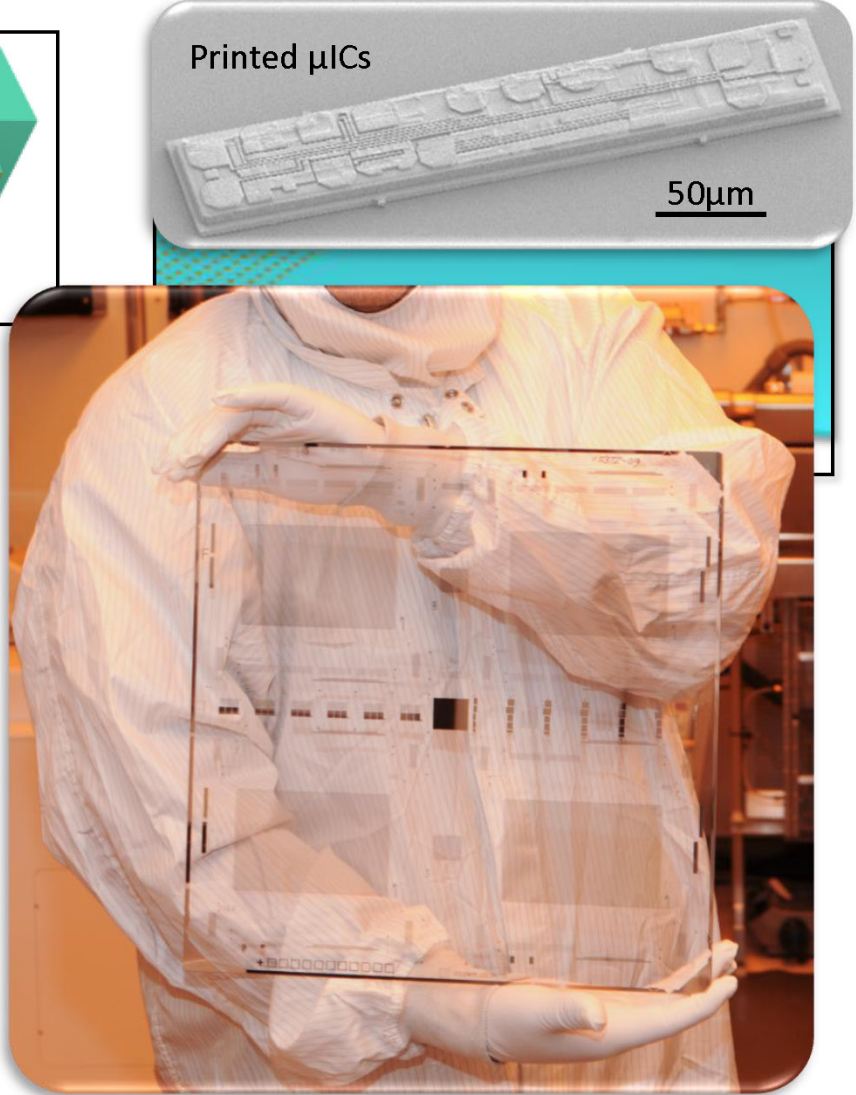
Precise, Deterministic Dispersal of Micro Devices



Source Wafer

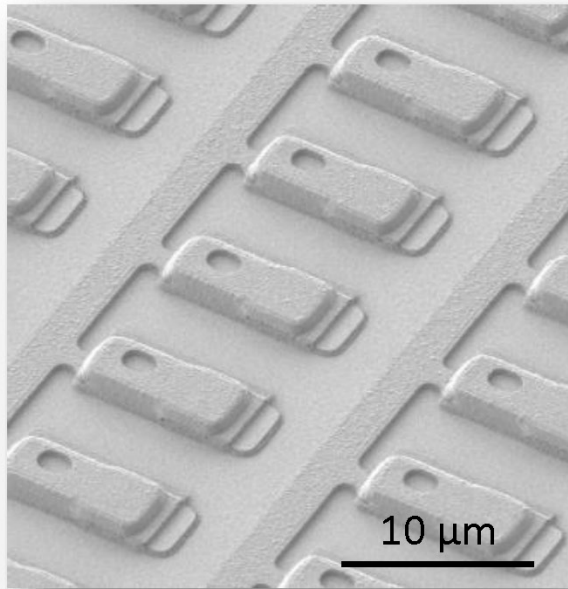


Printing
→

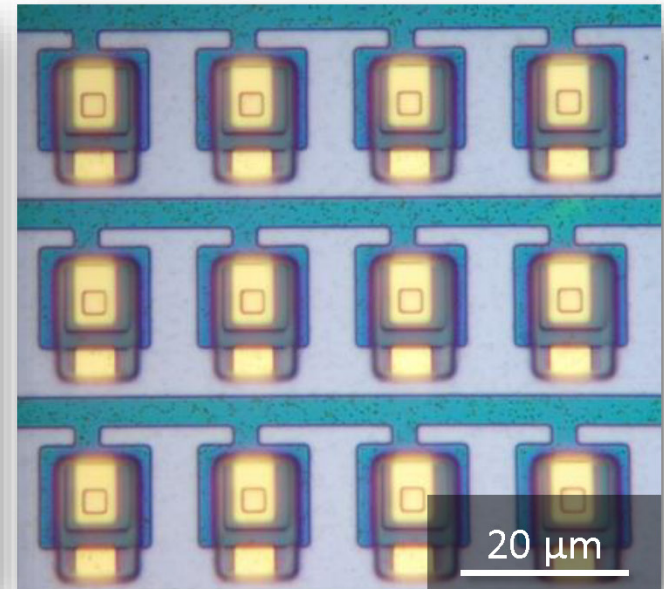
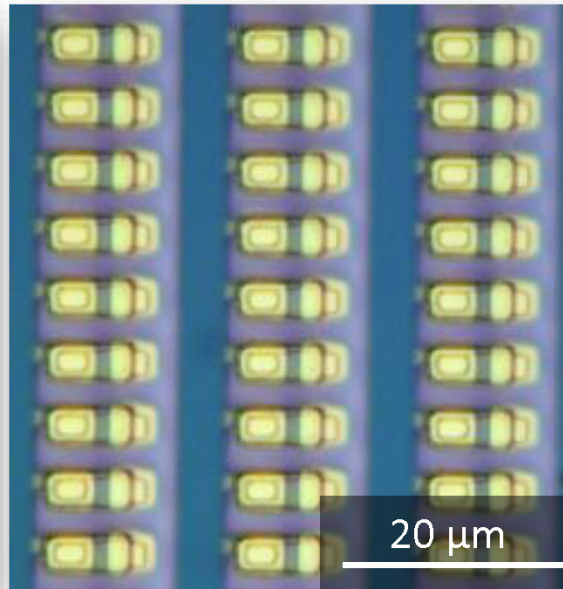


μ -LEDs Fabricated on Native Substrate

Horizontal iLEDs, variety of shapes & sizes.

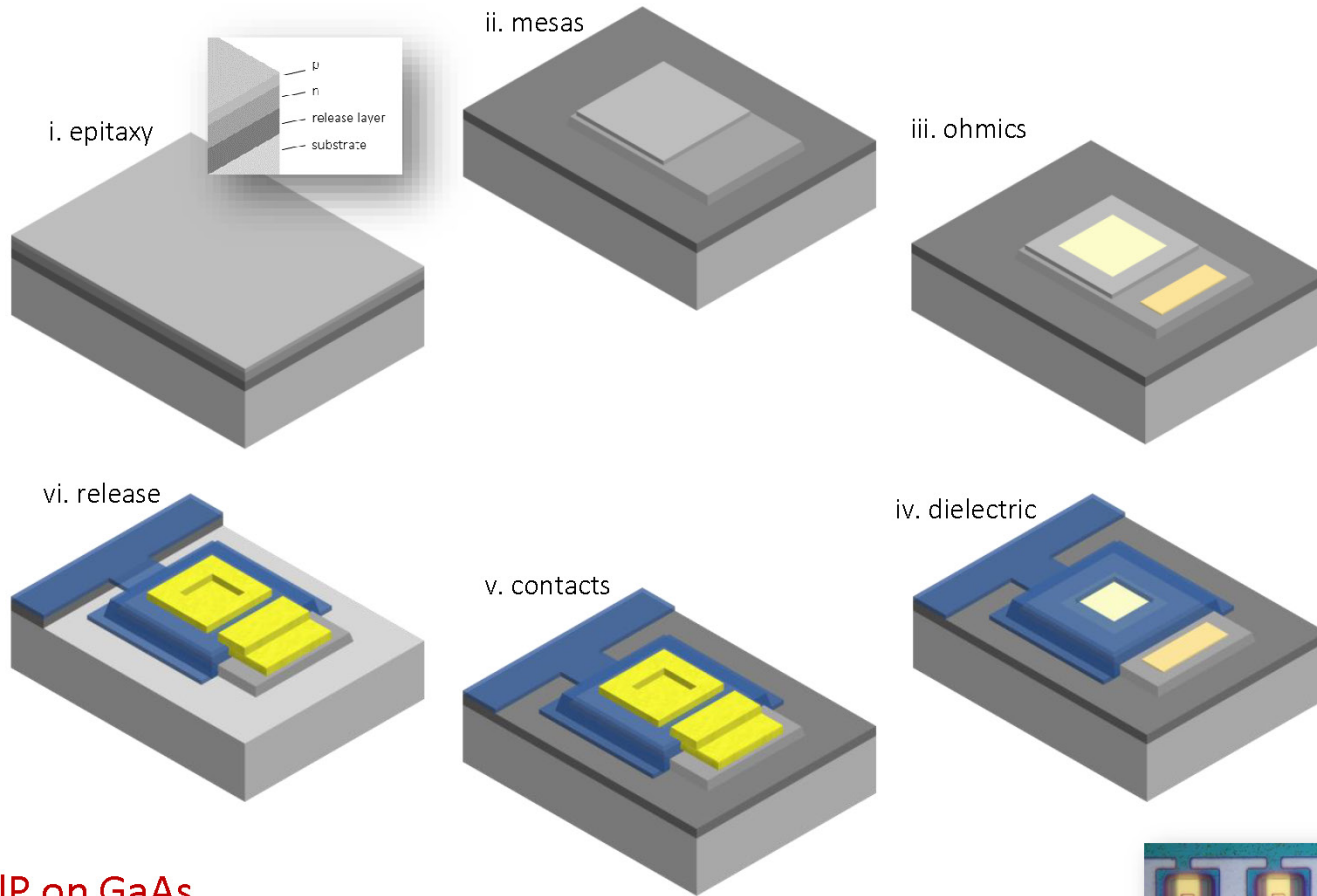


$3 \times 10 \mu\text{m}^2$



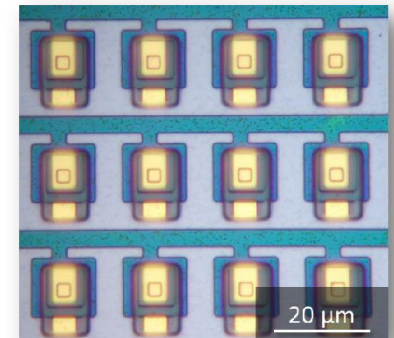
$8 \times 15 \mu\text{m}^2$

LED Fabrication Sequence

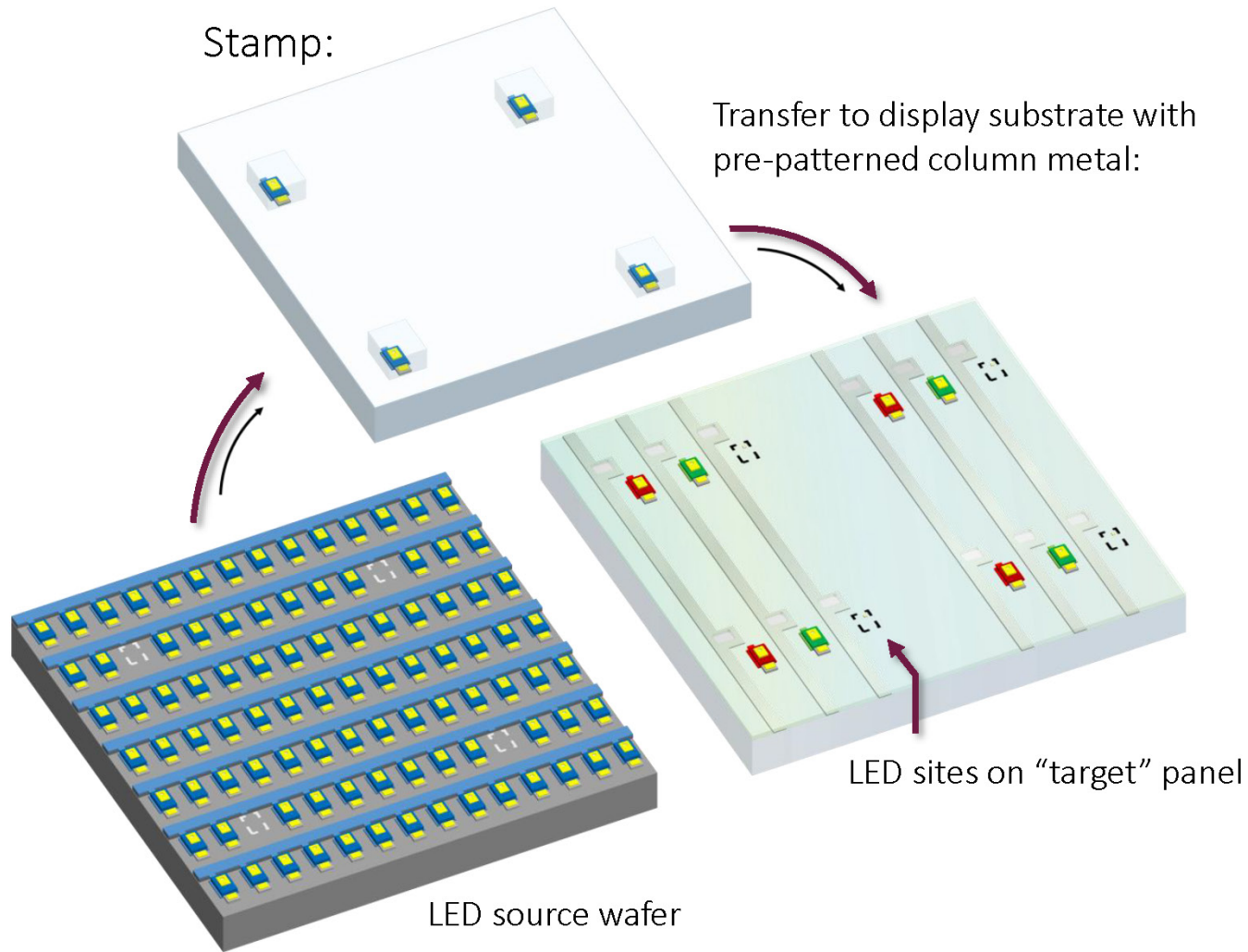


Red: InGaAlP on GaAs

Blue, Green: InGaN on Si



Transfer to Display Substrate

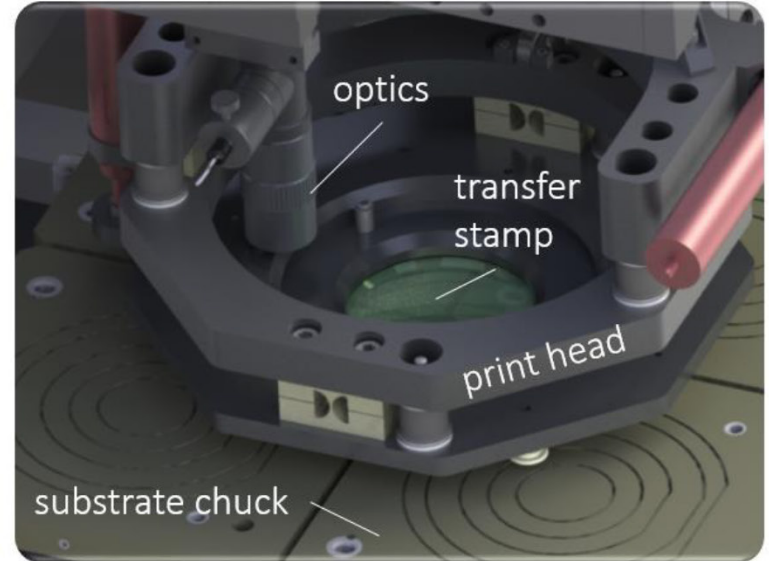
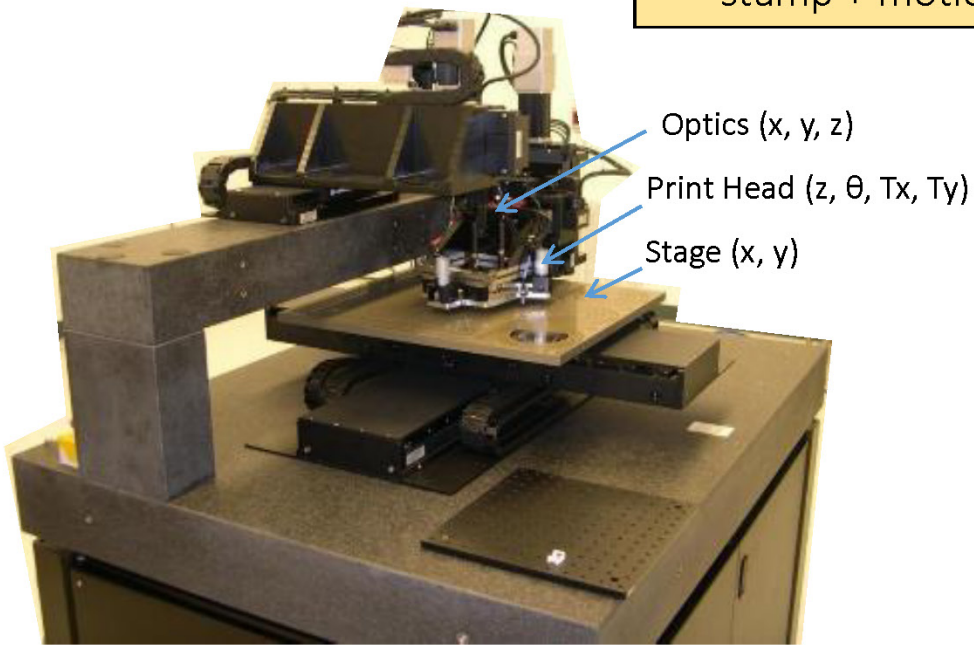


LED source wafer

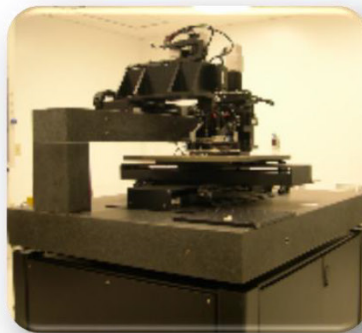
→ Different "source" for each color

Automated Micro Transfer Printing

stamp + motion + optics



Henderson, NC



Durham, NC



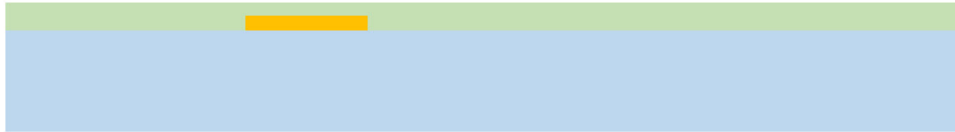
Tyndall, IE



RTP, NC

Micro Transfer Printed PMiLED Display Process Flow

form first metal on substrate and apply a dielectric layer



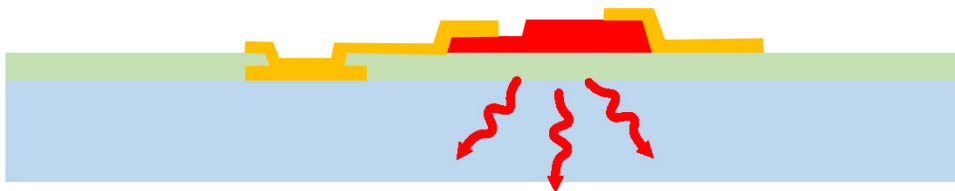
micro-transfer-printing of iLEDs



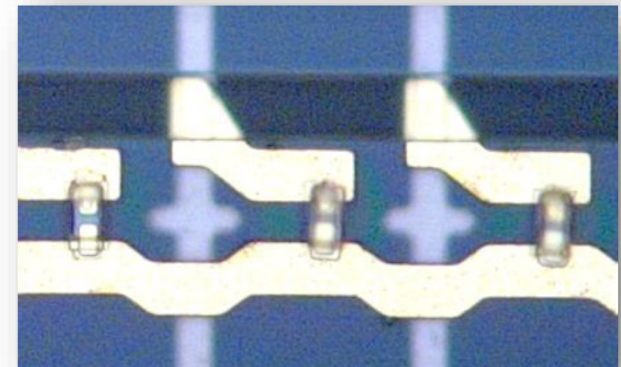
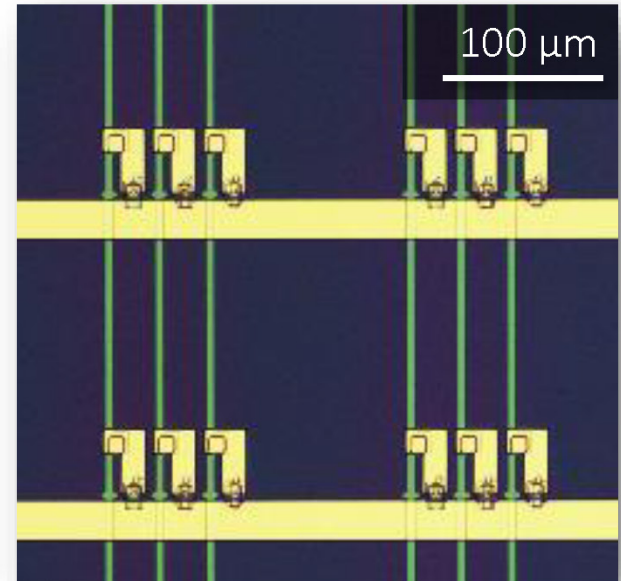
open via to first metal



form second metal that can connect iLED to first metal

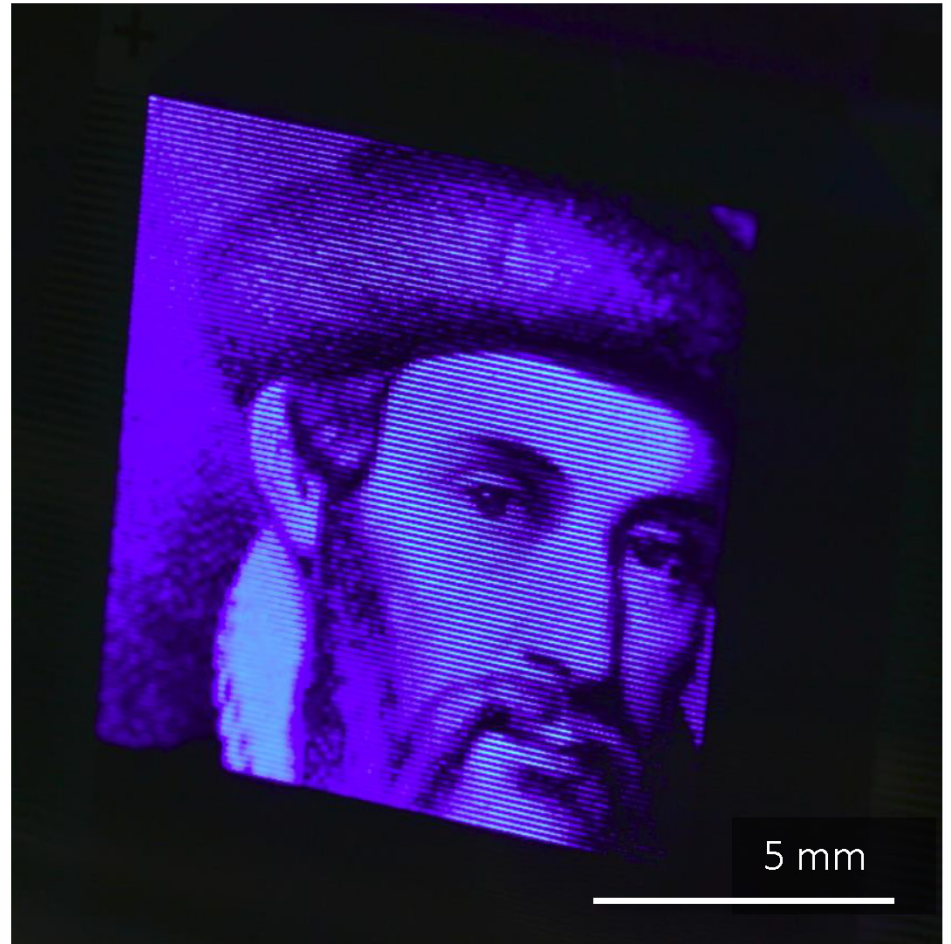
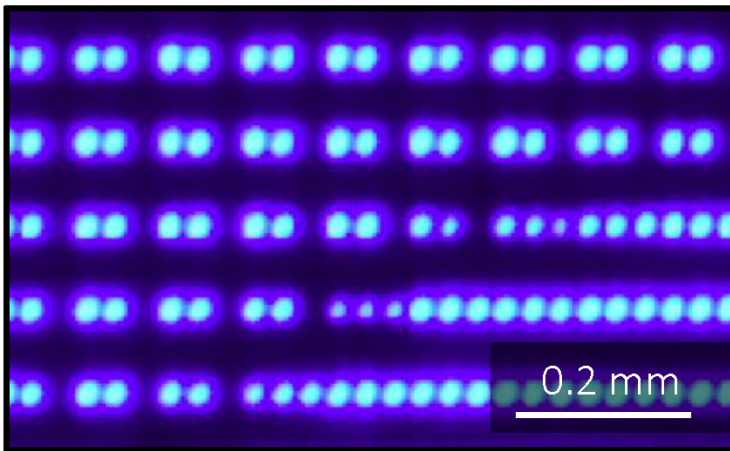


- substrate can be glass or plastic
- 3 photolithography levels



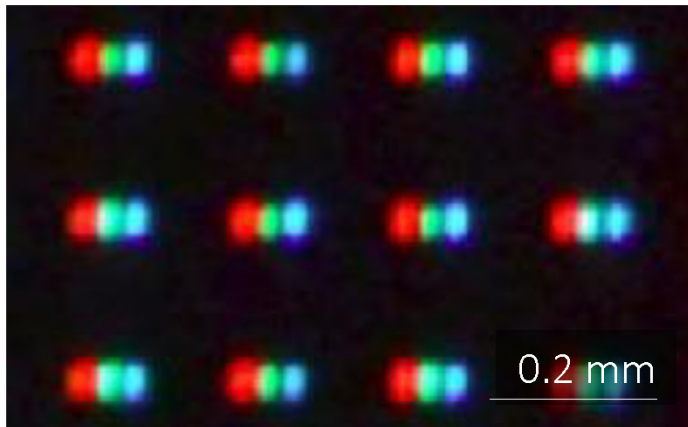
Monochrome Blue PMiLED

- 100 BBB x 100 pixels
- (3 blue LEDs per pixel)
- 100 μm pixel
- 10,000 posts on stamp
- 3 print operations



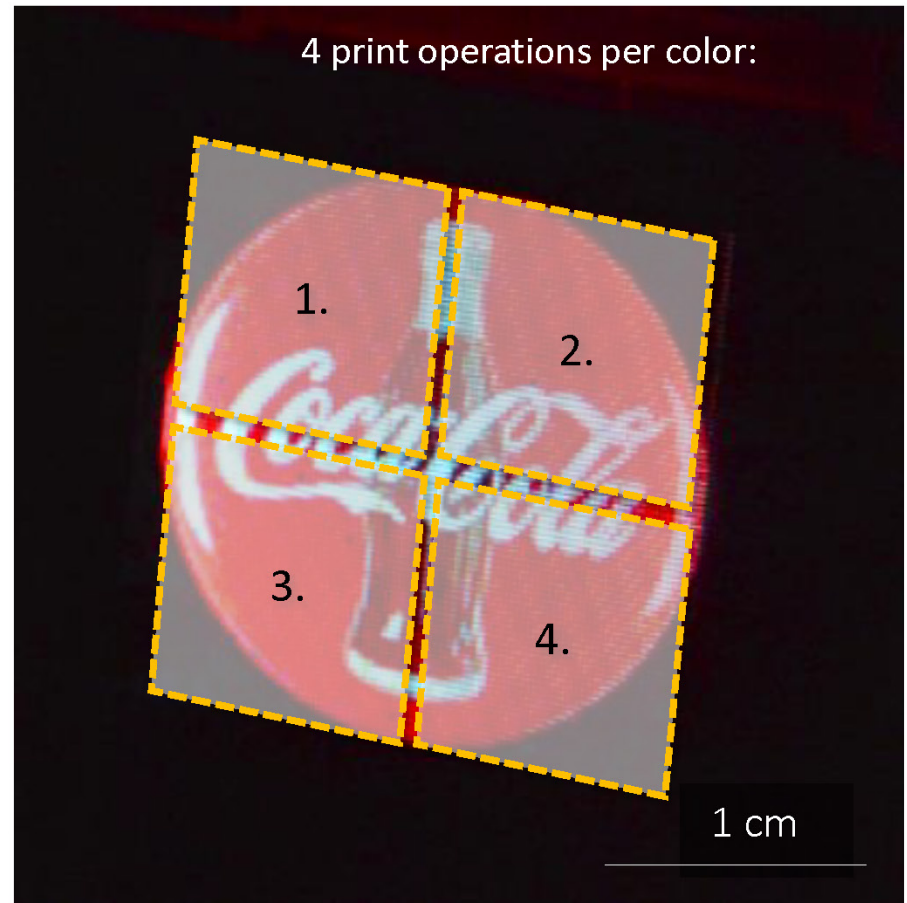
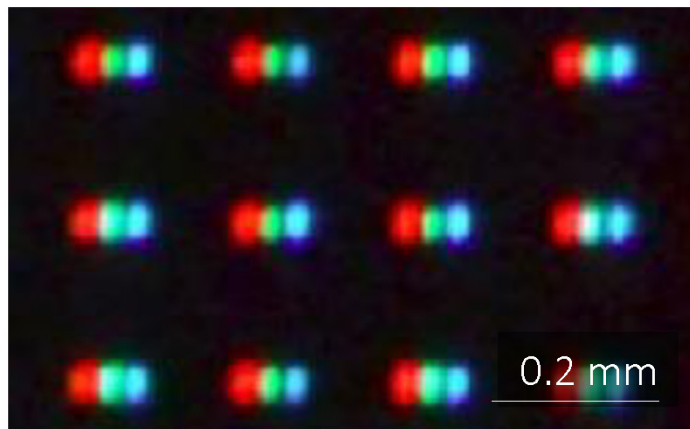
RGB PMiLED

- 100 RGB x 100 pixels
- 200 μm pixel
- 2,500 posts on stamp
- 12 print operations

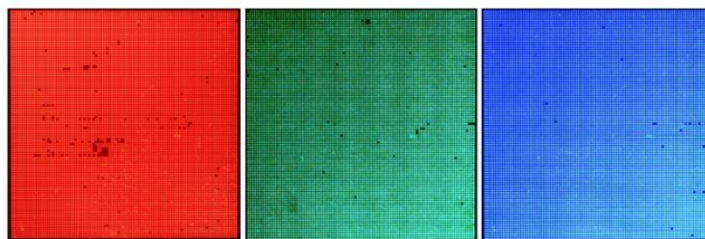
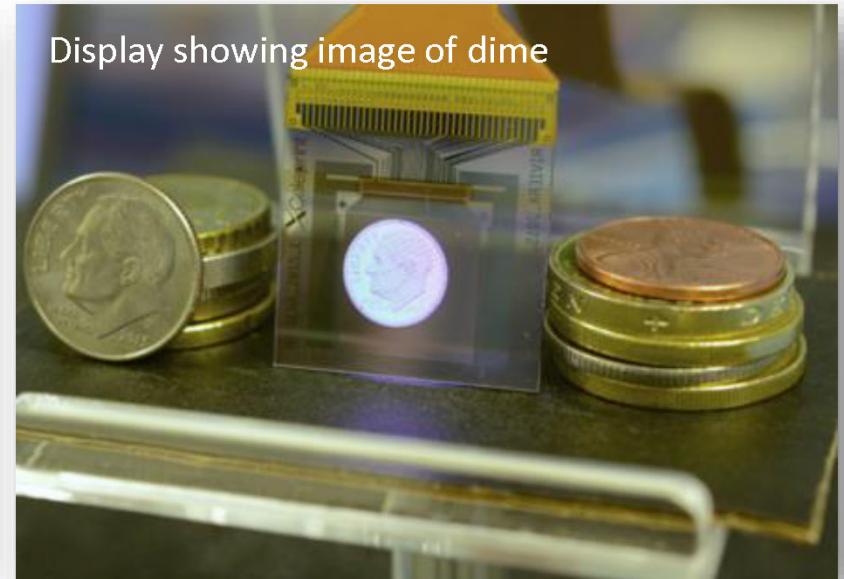
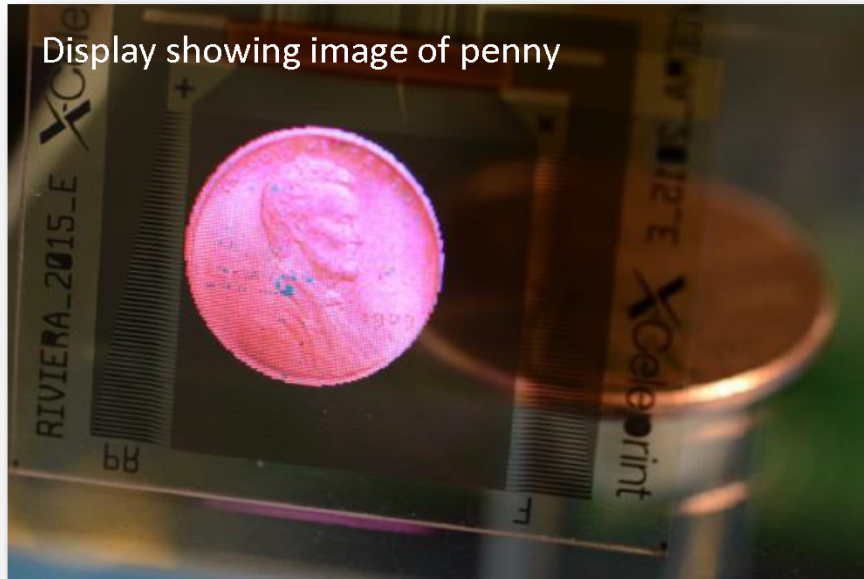


RGB PMiLED

- 100 RGB x 100 pixels
- 200 μm pixel
- 2,500 posts on stamp
- 12 print operations



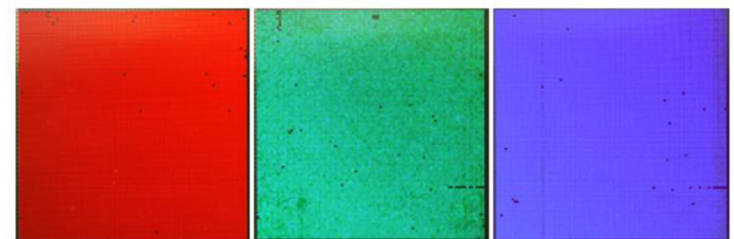
RGB PMiLED: Sub-Pixel Functional Yield



98.6%

99.7%

99.8%



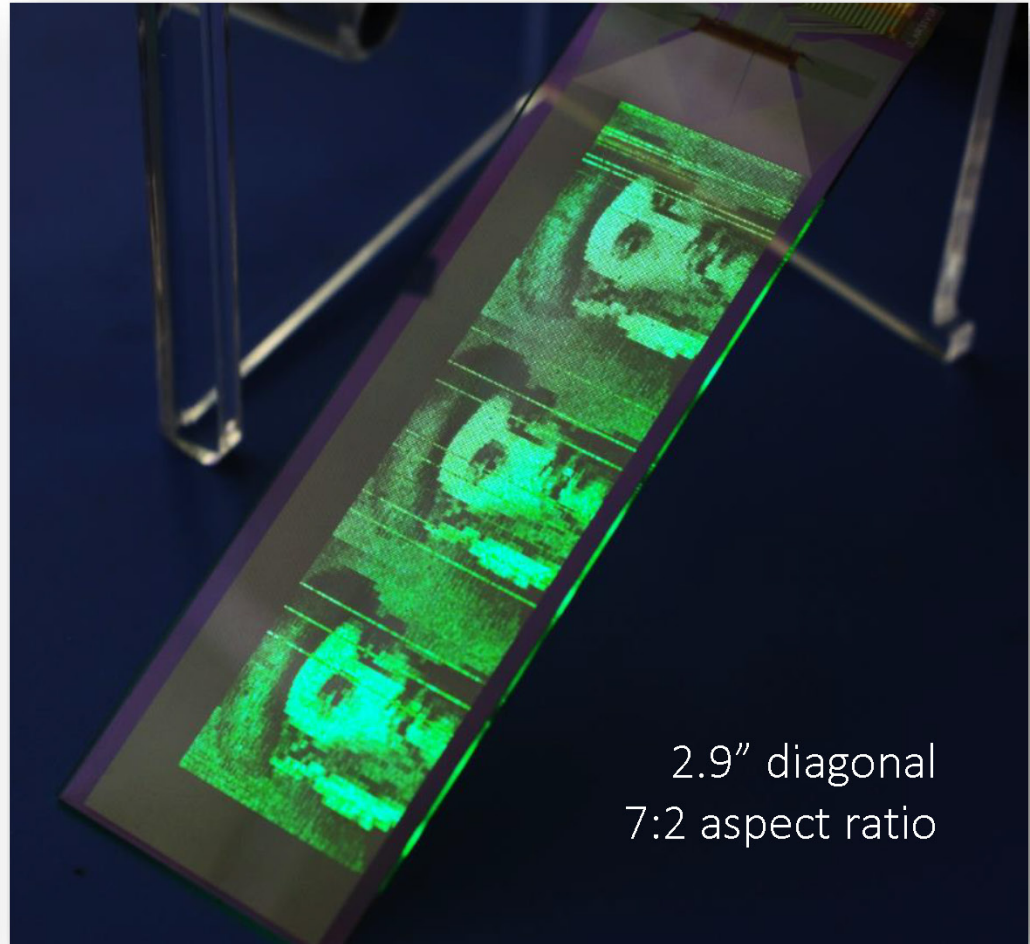
99.7%

99.5%

99.7%

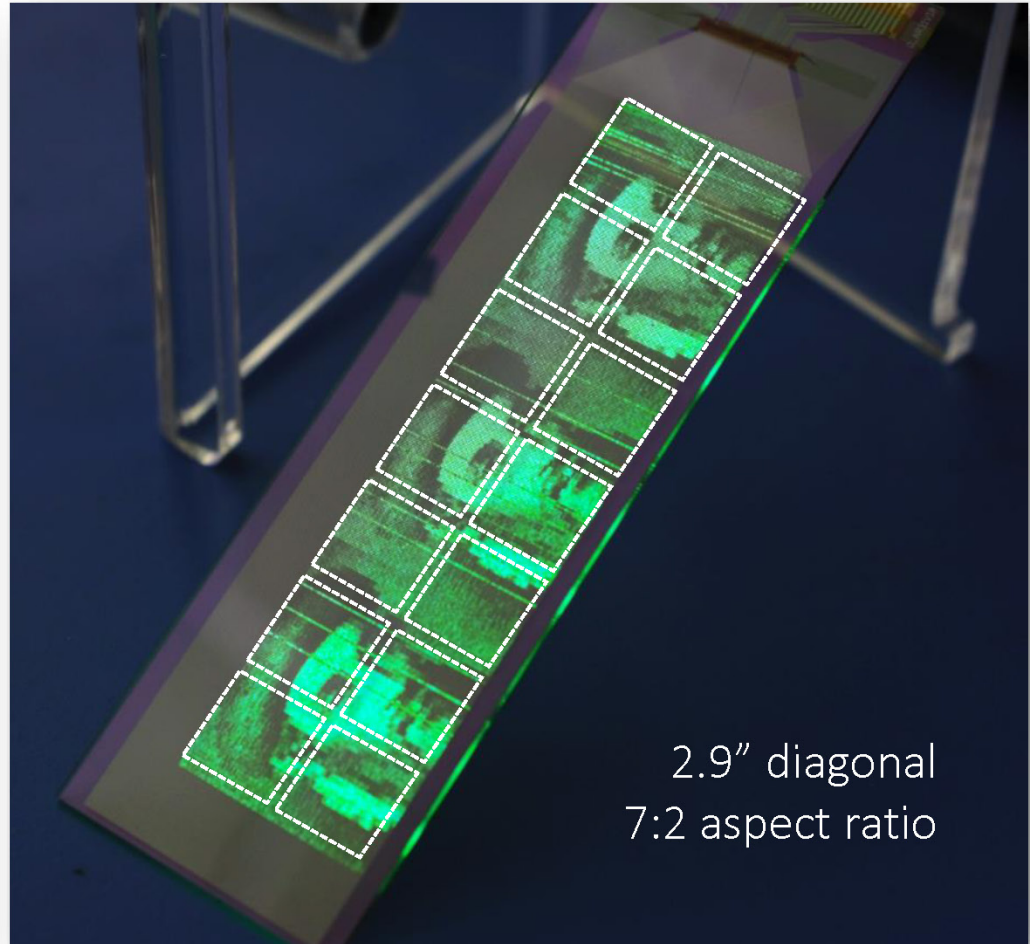
Band-Shaped Display

- 350 x 100 monochrome pixels
- 200 μm pixel
- 14 “prints” to populate display
 - 1 cm^2 stamp
 - 2,500 LEDs per print
- 7 x 2 cm^2



Band-Shaped Display

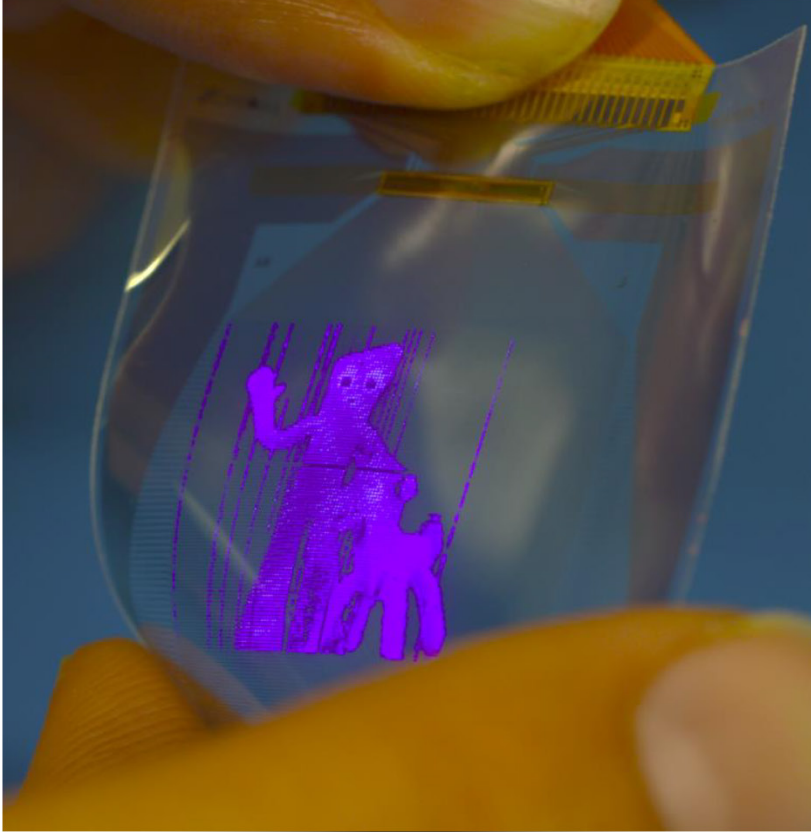
- 350 x 100 monochrome pixels
- 200 μm pixel
- 14 “prints” to populate display
 - 1 cm^2 stamp
 - 2,500 LEDs per print
- 7 x 2 cm^2



Band-Shaped Displays in Different Colors

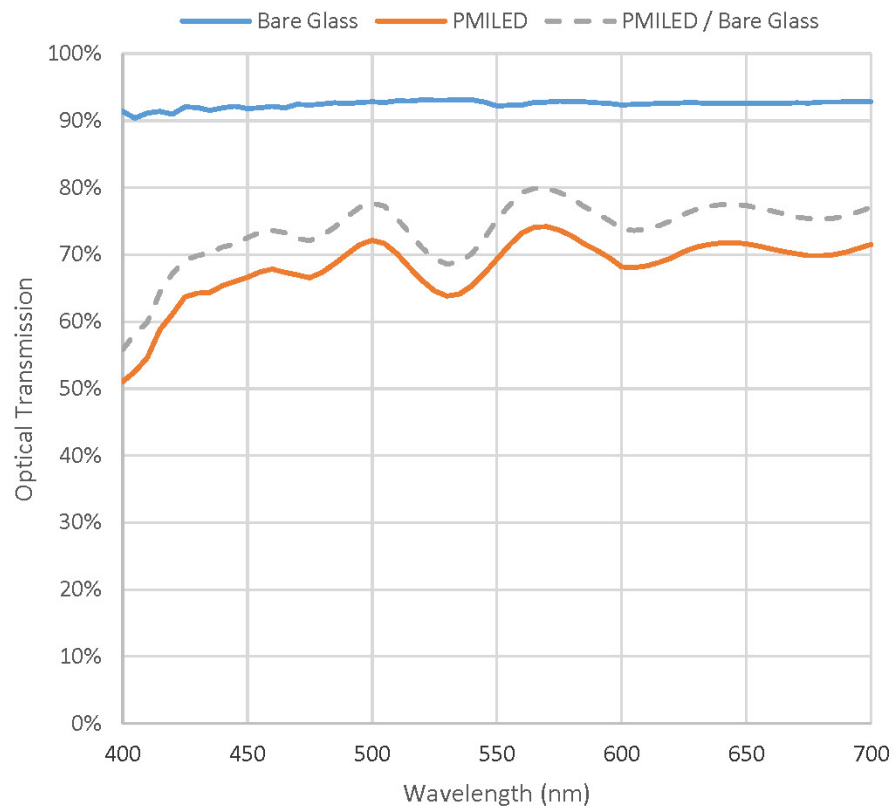
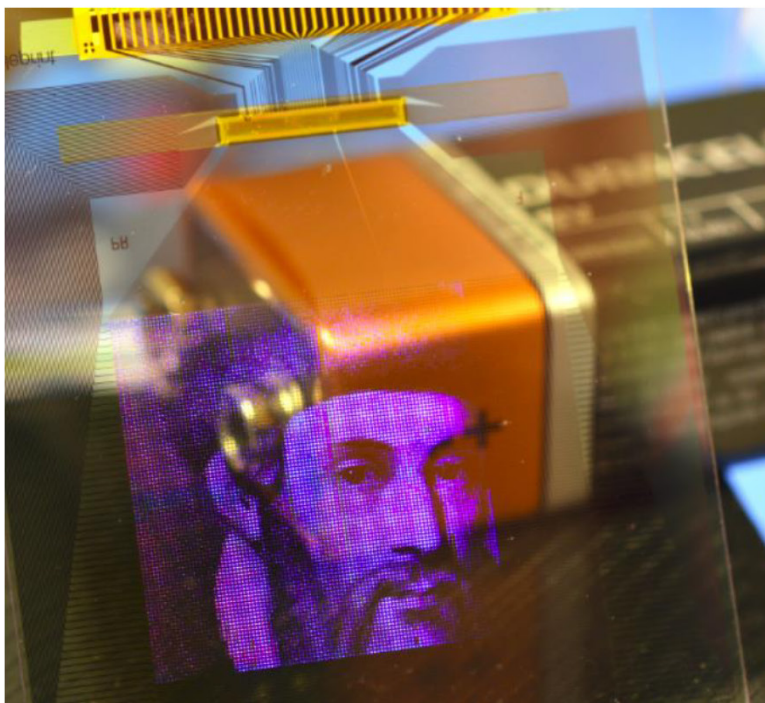


BBB PMiLED on Flex



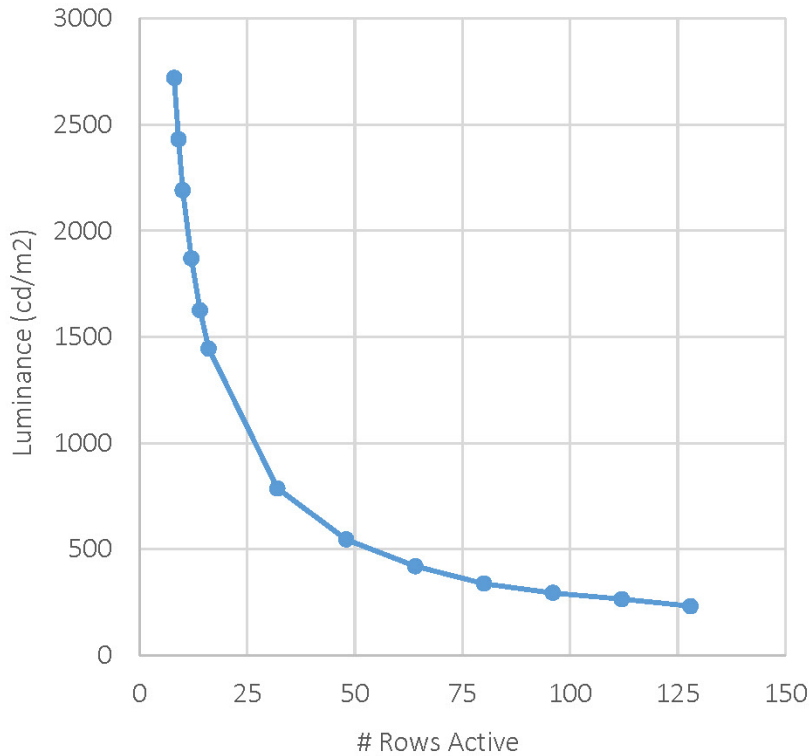
Transparency Monochrome Blue Display, 127 ppi

28 mm diagonal array of LEDs

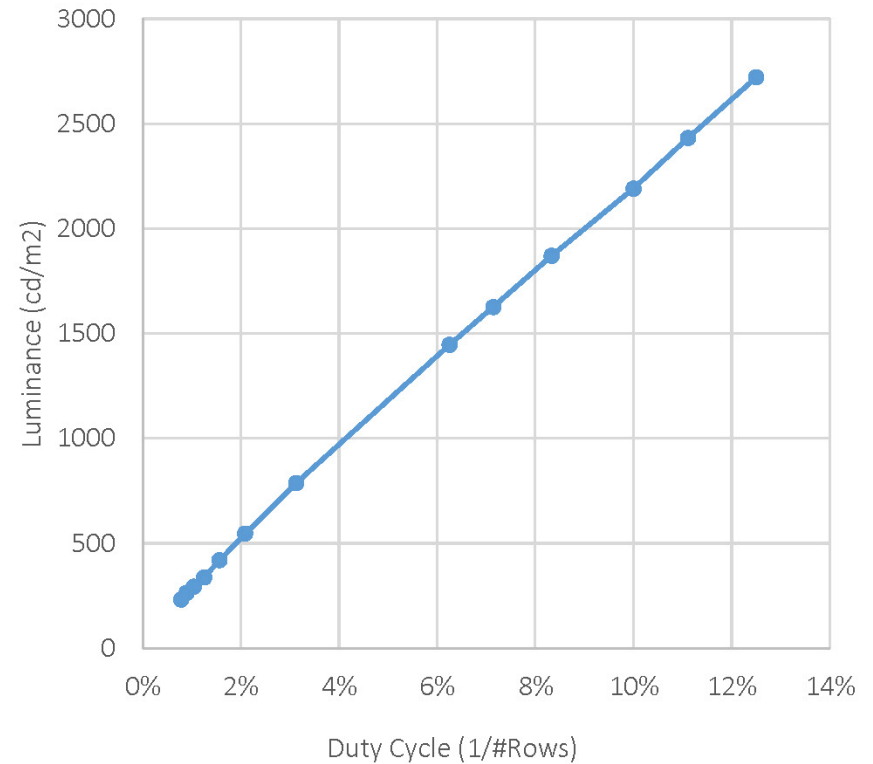


Brightness, Row Reduction

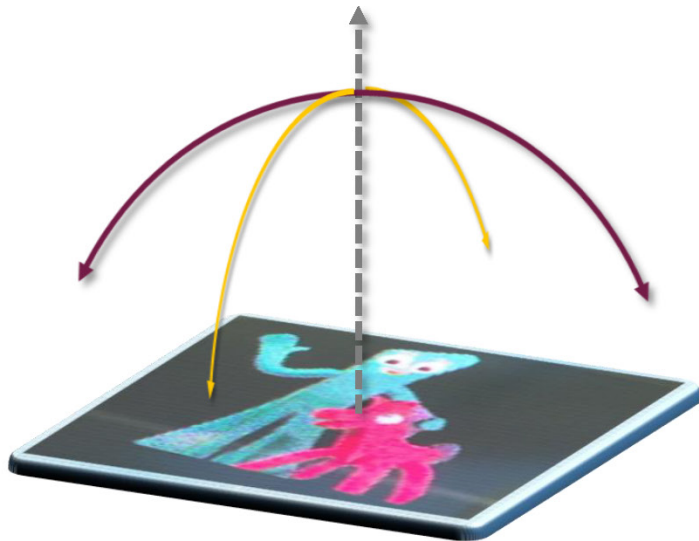
Luminance vs Number of Rows Active



Luminance vs Duty Cycle

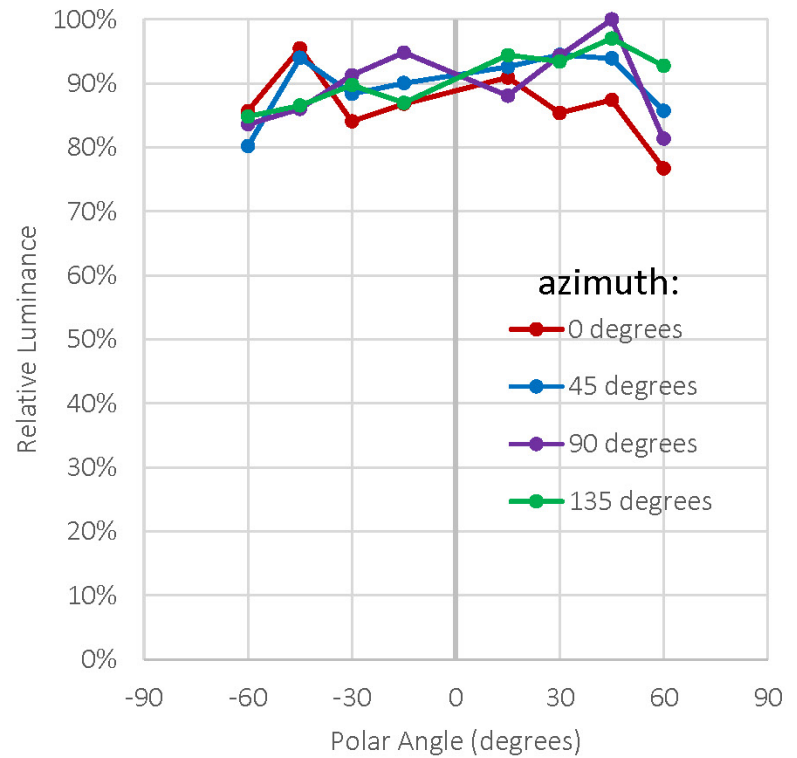


Effect of Viewing Angle on Luminance



LS-110 Luminance Meter

Luminance vs Viewing Angle



Luminance remains ~constant to +/- 60°

Electronic Repair: Activating Spare iLEDs



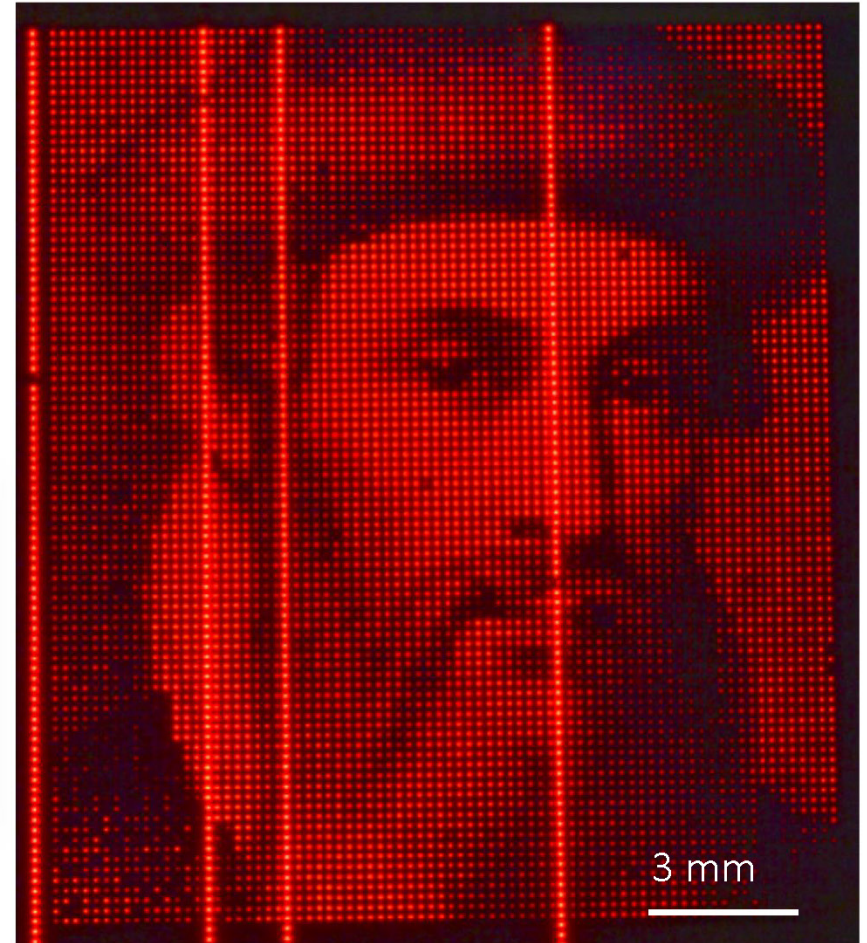
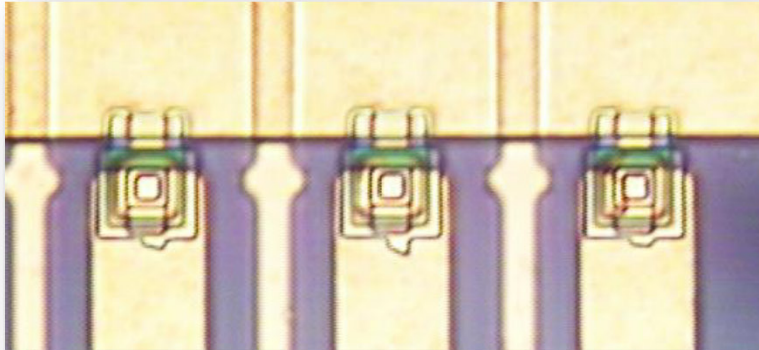
Activating Spare LEDs in BBB Display



Physical Repair

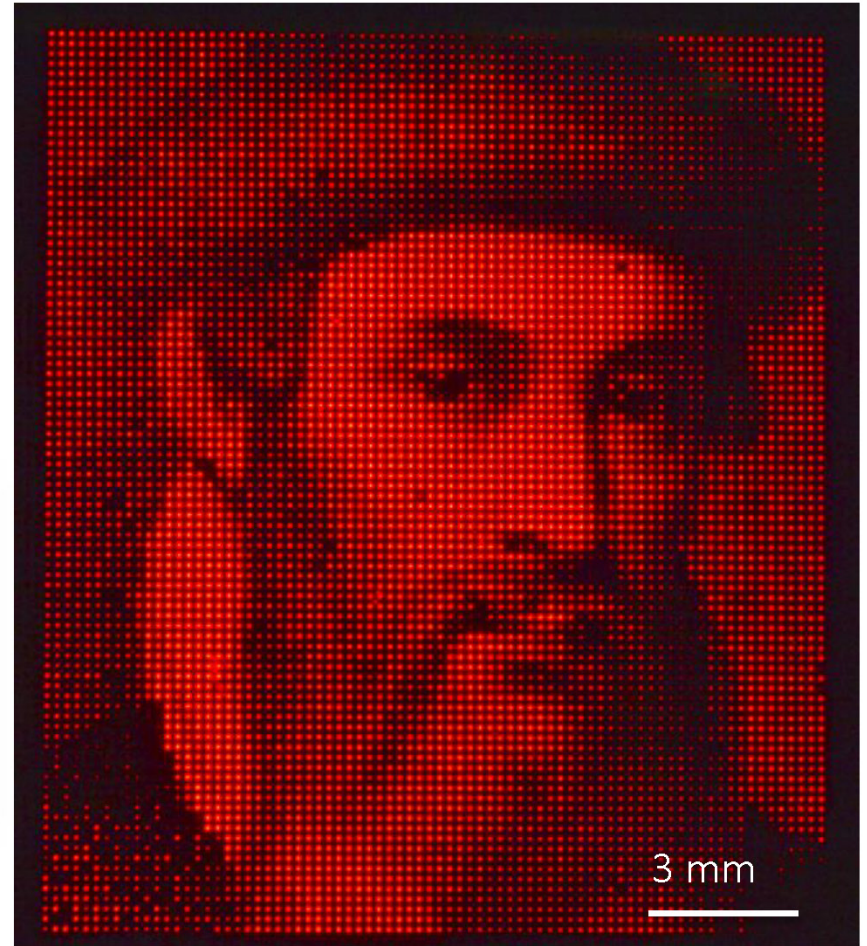
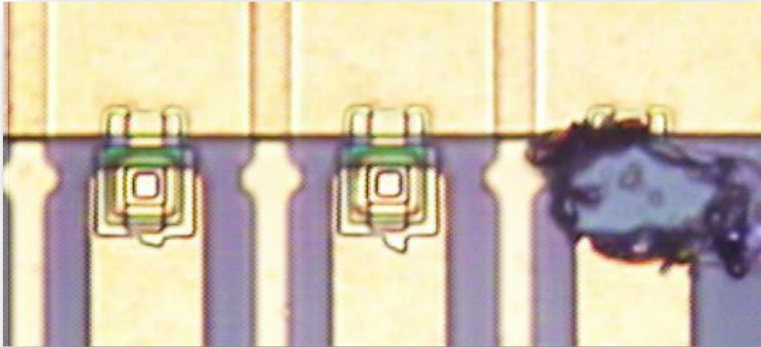
Shorted LEDs in PMiLED displays typically result in “always on” columns.

LEDs easily accessible during/after operation:



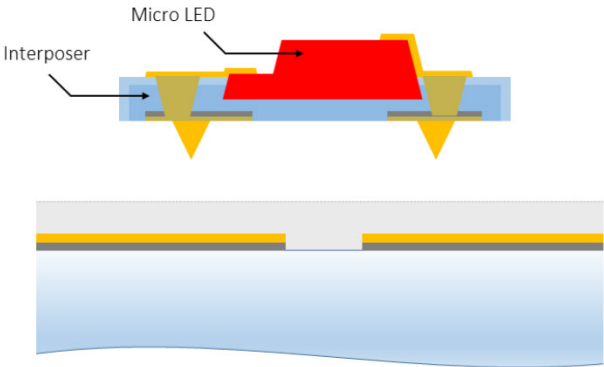
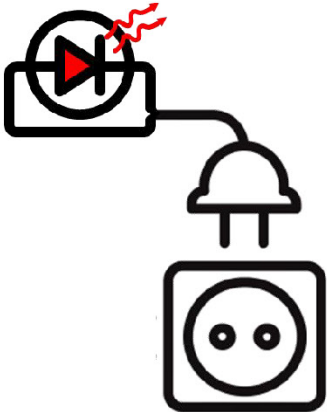
Physical Repair

Remove or disconnect shorted LEDs to clear column defect.



Current developments

- Finish display at printer: interconnect at print. Manufacture and repair.

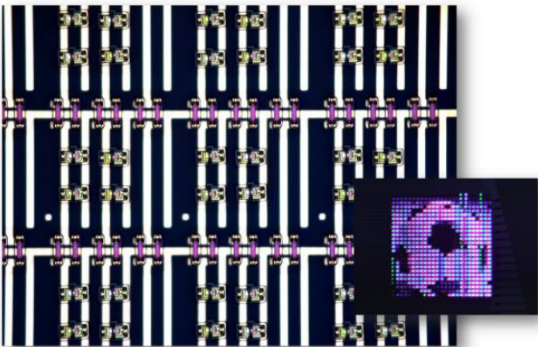
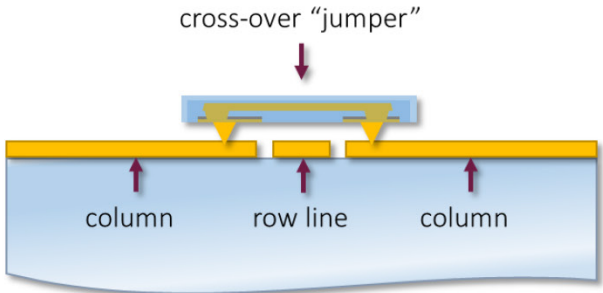


Prevatte, Carl, et al. "Pressure activated interconnection of micro transfer printed components." *Applied Physics Letters* (2016)

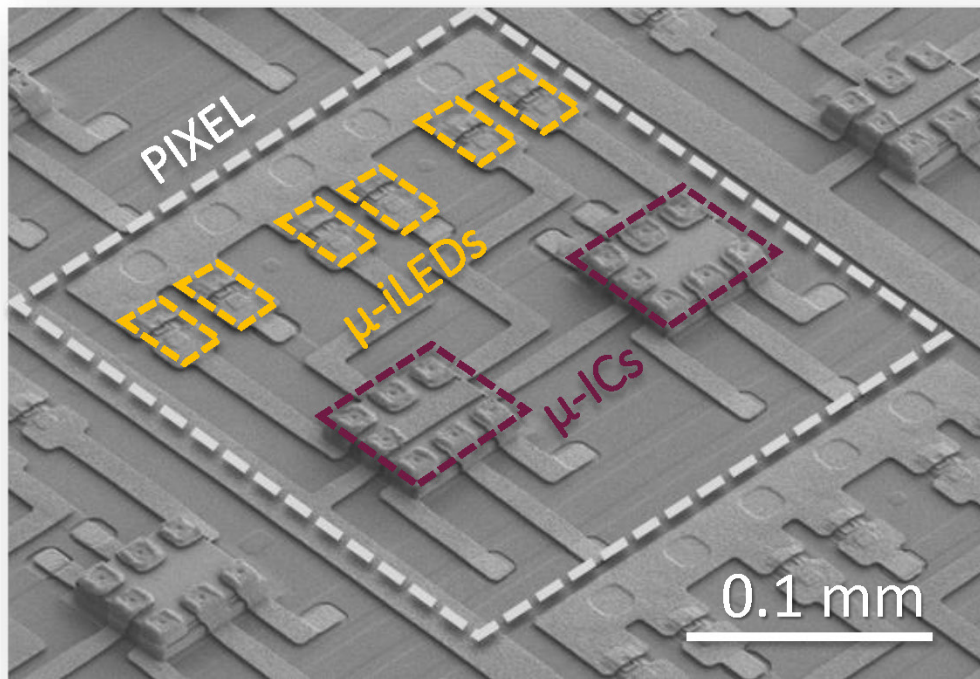
36 mm displays:
Finished at printer



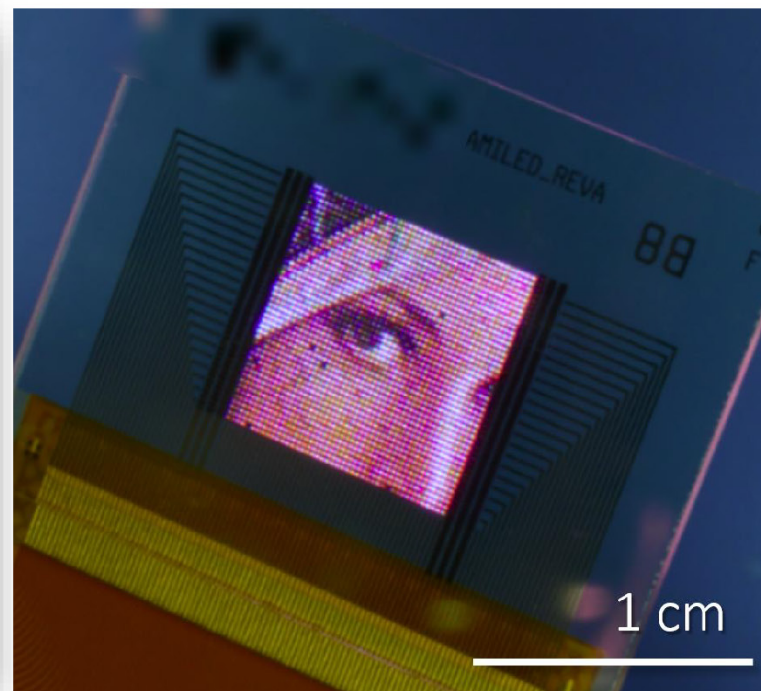
- Single-layer metal passive matrix with printed cross-overs:



Current Developments (2): Micro iLEDs and Micro Driver ICs for AMiLED



200 μ m pixels, six μ -iLEDs and two μ -ICs in each.
412 transistors per pixel; 1.8V & 5V, 180 nm CMOS.
Digital row and column inputs; current set in μ -ICs.



44 x 44 pixel display.
Active Matrix, Pulse-Width-Modulated.

Summary:

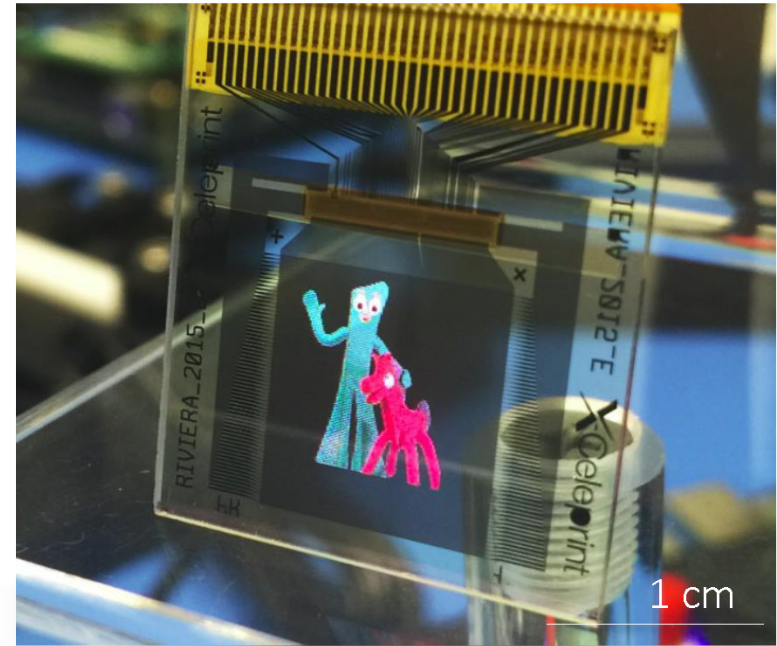
Passive matrix emissive displays fabricated on glass & plastic using arrays of transfer-printed inorganic LEDs.

- Variety of shapes and sizes, large-area processes
- RGB on non-native substrate

Interesting properties:

- Transparency, stacking, brightness, viewing angle.
- Repairable arrays, simplified panel fabrication.

Platform for advanced, multi-functional emissive displays.



Thanks from the X-Celeprint Team!

Matt Meitl, Dave Kneeburg, Dave Gomez, Sal Bonafede, Carl Prevatte, Paul Hines, Scott Goodwin, Kanchan Ghosal, Antonio Jose Trindade, Alin Fecioru, Bob Rotzoll, Sam Barnhill, Brad Krongard, Erich Radauscher, Brook Raymond, Tanya Moore, Ron Cok, Steven Kelleher, Raja Gull, George Melnik, Alexandre Chikhaoui, Kyle Benkendorfer

cbower@x-celeprint.com